

METHOD FOR FORMING AN ENCAPSULATED DEVICE AND STRUCTURE

Abstract of the Disclosure

5

In one embodiment, an electronic device package (1) includes a leadframe (2) with a flag (3). An electronic chip (8) is attached to the flag (3) with a die attach layer (9). A trench (16) having curved sidewalls is formed in the 10 flag (3) in proximity to the electronic chip (8) and surrounds the periphery of the chip (8). An encapsulating layer (19) covers the chip (8), portions of the flag (3), and at least a portion of the curved trench (16). The curved trench (16) reduces the spread of die attach material 15 across the flag (3) during chip attachment, which reduces chip and package cracking problems, and improves the adhesion of encapsulating layer (19). The shape of the curved trench (16) prevents flow of die attach material into the curved trench (16), which allows the encapsulating layer 20 (19) to adhere to the surface of the curved trench (16).